



PATENT / DOCKET NO.: 24061.231 / TSMC2003-1385
CUSTOMER NO.: 42717

INVENTOR'S DECLARATION FOR PATENT APPLICATION

As below named inventors, we hereby declare that:

Our residence, post office address and citizenship are as stated below next to our names;

We believe we are the original, first and sole joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled

LOGIC EMBEDDED-MEMORY INTEGRATED CIRCUITS

the specification of which: (check one)

 is attached hereto.

X was filed on April 16, 2004
under Attorney's Docket Number 24061.231 / TSMC2003-1385
as Application Serial No. 10/826,899
and was amended on _____ (if applicable).

We hereby authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.).

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the patentability of this application in accordance with 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF INVENTOR: Syun-Ming Jang

INVENTOR'S SIGNATURE: Sy - Ming Jang

DATED: April 20, 2004

RESIDENCE: Hsin-Chu, Taiwan, R.O.C.

POST OFFICE ADDRESS: 7F, No. 83, Kwung-Hua N. St.
Kwung-Hua Li
Hsin-Chu, Taiwan 300, R.O.C..

CITIZENSHIP: Taiwan, R.O.C.

FULL NAME OF INVENTOR: Horng-Huei Tseng

INVENTOR'S SIGNATURE: Horng-Huei Tseng

DATED: April 20, 2004

RESIDENCE: Hsin-Chu, Taiwan, R.O.C.

POST OFFICE ADDRESS: 2F, No.18-1, Lane 281
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CITIZENSHIP: Taiwan, R.O.C.

R-72474.1



Docket No. 24061.231/TSMC2003-1383
Customer No. 42717

UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Syun-Ming Jang, et al. § Docket No.: 24061.231/TSMC2003-1383
Serial No.: 10/826,899 § § Examiner: To Be Determined
Filed: April 26, 2004 § § Art Unit: 2812
For: Logic Embedded-Memory Integrated Circuits § § Conf. No.: 2231
§ §

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL SHEET TO POWER OF ATTORNEY

In accordance with 37 CFR 1.32 (c)(3) and with reference to the accompanying Power of Attorney, please recognize the following ten patent practitioners as being of record in this application.

Name	Registration Number
David M. O'Dell	42,044
Jeffrey M. Becker	35,442
Timothy F. Bliss	50,925
Andrew S. Ehmke	50,271
Dave R. Hofman	55,272
Wei Wei Jeang	33,305
Julie M. Nickols	50,826
J. Andrew Lowes	40,706
T. Murray Smith	30,222
Chien Wei Chou	41,672

Respectfully submitted,

David M. O'Dell
Registration No. 42,044

Dated: 8-25-04

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Certificate of Mailing

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.

Name

8-26-04

Date



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Syun-Ming Jang et al.

Serial No.: Unknown

Filed: Herewith

For: Logic Embedded-Memory Integrated Circuits

§ Attorney Docket No.: 24061.231
§ TSMC2003-1385
§ Customer No. 27683
§ Group Art Unit: Unknown
§ Examiner: Unknown
§

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

POWER OF ATTORNEY FOR PATENT APPLICATION

As a representative of the Assignee, Taiwan Semiconductor Manufacturing Company, Ltd., I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

David L. McCombs (Reg. No. 32,271); Jeffrey M. Becker (Reg. No. 35,442); James R. Bell (Reg. No. 26,528); Timothy F. Bliss (Reg. No. 50,925); Randall C. Brown (Reg. No. 31,213); Randall E. Colson (Reg. No. 40,566); Michael A. Davis, Jr. (Reg. No. 35,488); Andrew S. Ehmke (Reg. No. 50,271); Priscilla Ferguson (Reg. No. 42,531); Sarah T. Harris (Reg. No. 35,891); William E. Hickman (Reg. No. 46,771); David R. Hofman (Reg. No. P-55,727); Rita M. Irani (Reg. No. 31,028); Wei Wei Jeang (Reg. No. 33,305); Warren B. Kice (Reg. No. 22,732); J. Andrew Lowes (Reg. No. 40,706); Todd Mattingly (Reg. No. 40,298); Julie Nickols (Reg. No. 50,826); Gloria Norberg (Reg. No. 36,706); David M. O'Dell (Reg. No. 42,044); T. Murray Smith (Reg. No. 30,222); and Chien Wei Chou (Reg. No. 41,672).

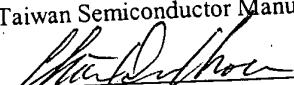
Please address all correspondence and telephone calls regarding this application to:

David M. O'Dell
Attorney for Applicants
Haynes and Boone, LLP
901 Main Street, Suite 3100
Dallas, TX 75202-3789
972-739-8635 / 214-200-0853 - Fax

The undersigned is the representative for the Assignee of the entire right, title, and interest in the patent application identified above. A copy of the assignment or other documents in the chain of title are attached.

The undersigned (whose title is supplied below) is authorized to act on behalf of the Assignee.

Taiwan Semiconductor Manufacturing Company, Ltd.


Chien-Wei Chou
Title: Director, IP Division

Date

A S S I G N M E N T

WHEREAS, we,

(1)	Syun-Ming Jang	of	7F, No. 83, Kwung-Hua N. St. Kwung-Hua Li Hsin-Chu, Taiwan 300, R.O.C..
(2)	Horng-Huei Tseng	of	2F, No.18-1, Lane 281 Zhong-Yung Rd. Hsin-Chu, Taiwan 300, R.O.C

have invented certain improvements in

LOGIC EMBEDDED-MEMORY INTEGRATED CIRCUITS

for which we have executed an application for Letters Patent of the United States of America,

X of even date filed herewith; and
filed on April 16, 2004 and assigned application number 10/826,899; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

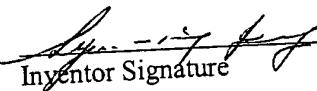
AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal

proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Syun-Ming Jang

Residence Address: 7F, No. 83, Kwung-Hua N. St.
Kwung-Hua Li
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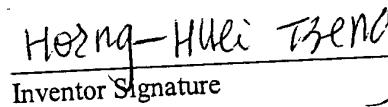
Dated: April 20, 2004


Inventor Signature

Inventor Name: Horng-Huei Tseng

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Taiwan, R.O.C.

Dated: April 20, 2004


Inventor Signature

R-72473.1